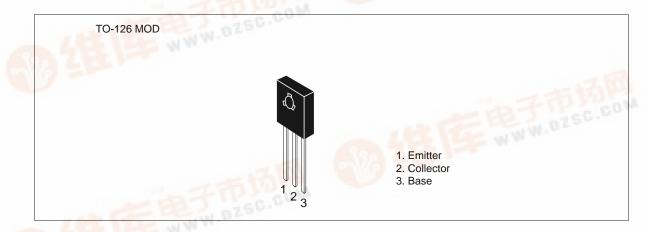
Silicon PNP Epitaxial

HITACHI

Application

Low frequency power amplifier complementary pair with 2SD669/A

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

		Ratings		
Item	Symbol	2SB649	2SB649A	Unit
Collector to base voltage	V_{CBO}	-180	-180	V
Collector to emitter voltage	V_{CEO}	-120	-160	V
Emitter to base voltage	$V_{\scriptscriptstyle{EBO}}$	- 5	- 5	V
Collector current	I _c	-1.5	-1.5	Α
Collector peak current	I _{C(peak)}	-3	-3	Α
Collector power dissipation	P _c	1	1	W
	P _C *1	20	20	W
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

Note: 1. Value at $T_c = 25^{\circ}C$

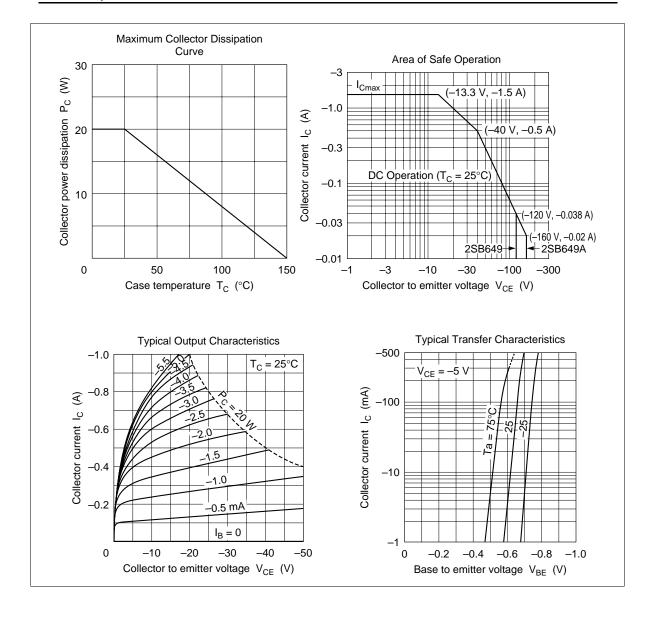
Electrical Characteristics ($Ta = 25^{\circ}C$)

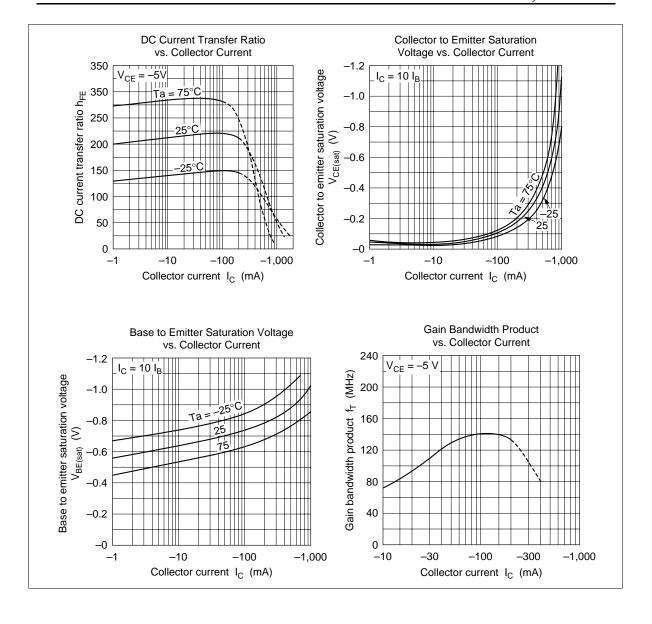
		2SB6	49		2SB649A				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-180	_	_	-180	_	_	V	$I_{\rm C} = -1 \text{ mA}, I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-120	_	_	-160	_	_	V	$I_{\rm C} = -10$ mA, $R_{\rm BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5	_	_	- 5	_	_	V	$I_{E} = -1 \text{ mA}, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-10	_	_	-10	μΑ	$V_{CB} = -160 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE1} *1	60	_	320	60	_	200		$V_{CE} = -5 \text{ V},$ $I_{C} = -150 \text{ mA}$
	h _{FE2}	30	_	_	30	_	_		$V_{CE} = -5 \text{ V},$ $I_{C} = -500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-1	_	_	-1	V	$I_{\rm C} = -500 \text{ mA},$ $I_{\rm B} = -50 \text{ mA}$
Base to emitter voltage	V_{BE}	_	_	-1.5	_	_	-1.5	V	$V_{CE} = -5 \text{ V},$ $I_{C} = -150 \text{ mA}$
Gain bandwidth product	f _T	_	140	_	_	140	_	MHz	$V_{CE} = -5 \text{ V},$ $I_{C} = -150 \text{ mA}$
Collector output capacitance	Cob	_	27			27		pF	$V_{CB} = -10 \text{ V}, I_{E} = 0,$ f = 1 MHz

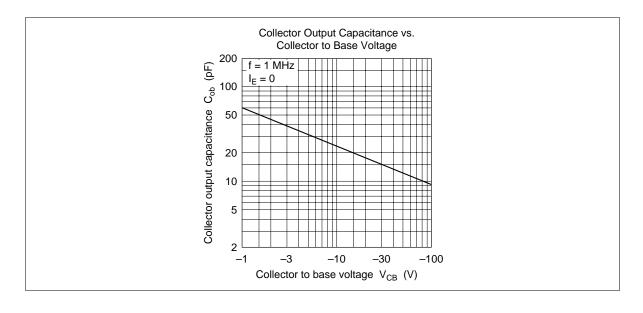
Notes: 1. The 2SB649 and 2SB649A are grouped by h_{FE1} as follows.

2. Pulse test

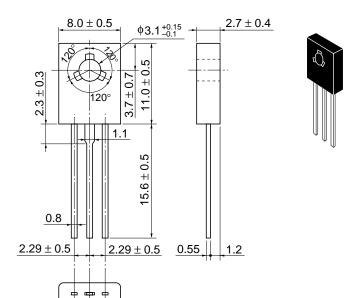
	В	С	D
2SB649	60 to 120	100 to 200	160 to 320
2SB649A	60 to 120	100 to 200	_











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